Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-17 (Canceled)

Claim 18 (Currently amended): A method of electrically connecting an electronic device to a substrate, said method comprising:

passing free ends of a plurality of elongate spring contacts attached to said electronic device into a plurality of rigid, conductive recesses in said substrate, each said recess comprising a bottom portion disposed within said substrate that prevents said free ends from passing through said substrate; and

applying a force to said electronic device and thereby pressing said free ends against said bottom portions of said rigid, conductive recesses , wherein electrical connections between said elongate spring contacts and said rigid, conductive recesses are established and maintained substantially entirely due to said pressing.

Claim 19 (Previously presented): The method of claim 18, wherein said electronic device comprises a semiconductor device.

Claim 20 (Previously presented): The method of claim 18, wherein each of said recesses is V shaped.

Claim 21 (Previously presented): The method of claim 18, wherein each of said recesses is U shaped.

Claim 22 (Previously presented): The method of claim 18, wherein each of said recesses is trapezoidal shaped.

Claim 23 (Previously presented): The method of claim 18, wherein each of said recesses is wider near a surface of said substrate than within said substrate.

Claim 24 (Previously presented): The method of claim 18, wherein each of said recesses extends into said substrate and is tapered inwardly.

Claim 25 (Previously presented): The method of claim 18 further comprising removing said force, wherein said electrical connections are substantially eliminated.

Claim 26 (New): A method of electrically connecting an electronic device to a substrate having a surface and a plurality of rigid conductive terminals disposed adjacent said surface, said method comprising:

providing an electronic device having a plurality of elongate, spring contact elements for providing signal inputs to and/or outputs from said electronic device; and

pressing tips of ones of said spring contact elements against ones of said rigid conductive terminals and thereby generating in said spring contact elements spring forces that are perpendicular with respect to said surface of said substrate, wherein electrical connections between said elongate spring contacts and said rigid terminals are established and maintained substantially entirely due to said pressing.

Claim 27 (New): The method of claim 26, wherein:

said terminals comprise recesses in said substrate, and

said step of pressing comprises passing said tips through said recesses.

Claim 28 (New): The method of claim 27, wherein each said recess comprises a bottom against which one of said tips is pressed.

Claim 29 (New): The method of claim 28, wherein said bottom prevents said tips from passing through said substrate.

Claim 30 (New): The method of claim 29, wherein said recesses are cone shaped.

Claim 31 (New): The method of claim 29, wherein said recesses are concave.

Claim 32 (New): The method of claim 29, wherein each of said recesses is V shaped.

Claim 33 (New): The method of claim 29, wherein each of said recesses is U shaped.

Claim 34 (New): The method of claim 29, wherein each of said recesses is trapezoidal shaped.

Claim 35 (New): The method of claim 29, wherein each of said recesses is wider near a surface of said substrate than within said substrate.

Claim 36 (New): The method of claim 29, wherein each of said recesses extends into said substrate and is tapered inwardly.

Claim 37 (New): The method of claim 26 further comprising removing said force, wherein said electrical connections are substantially eliminated.